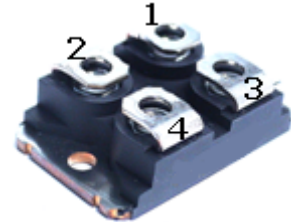
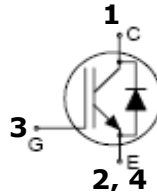


PRELIMINARY DATASHEET
IGBT in Trench & Field Stop technology with soft, fast recovery anti-parallel diode, in Isolated SOT227 Package

- Very high switching speed
- Very low $V_{CE(sat)}$
- Designed for frequency converters and UPS
- Very tight parameter distribution
- High ruggedness, temperature stability
 - parallel switching capability
- Very soft, fast recovery anti-parallel diode
- Pb-free lead finish; RoHS compliant


MAXIMUM RATINGS, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Units
Collector-emitter voltage	V_{CE}	600	V
DC collector current, limited by T_{jmax} $T_C = 80^\circ\text{C}$	I_C	100	A
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpulse}	200	
Diode forward current	I_F	75	
Gate-emitter voltage	V_{GE}	± 20	V
Operating junction and storage temperature	T_j, T_{stg}	-40... +175	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Max. Value	Units
Characteristics			
IGBT thermal resistance, junction to case	R_{thJC}	0.45	K/W
Diode thermal resistance, junction to case	R_{thJCD}	0.95	
Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-2 seconds)	V_{iso}	3000	V

¹ Allowed number of short circuits: < 1000; time between short circuits: > 1s.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

ELECTRICAL CHARACTERISTICS, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{V}$, $I_C = 75\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- -	1.45 1.7	1.9 -	V
Diode forward voltage	V_F	$V_{GE} = 0\text{V}$, $I_F = 75\text{A}$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	1.55 1.45	1.95 -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 1.2\text{mA}$, $V_{CE} = V_{GE}$	4.9	5.8	6.5	
Zero gate voltage collector current	I_{CES}	$V_{CE} = 600\text{V}$, $V_{GE} = 0$	-	-	1.0	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}$, $V_{GE} = 20\text{V}$	-	-	100	nA
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{CE} = 25\text{V}$, $V_{GE} = 0\text{V}$, $f = 1\text{MHz}$	-	6200	-	pF
Output capacitance	C_{oss}		-	384	-	
Reverse transfer capacitance	C_{rfs}		-	190	-	
Gate charge	Q_{Gate}		$V_{GE} = 15\text{V}$	-	1000	-

SWITCHING CHARACTERISTICS, Inductive Load at $T_j = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC} = 300\text{V}$, $I_C = 100\text{A}$, $V_{GE} = \pm 15\text{V}$, $R_G = 24\Omega$	-	100	-	ns
Rise time	t_r		-	60	-	
Turn-off delay time	$t_{d(off)}$		-	600	-	
Fall time	t_f		-	70	-	
Turn-on energy	E_{on}		-	4.85	-	mJ
Turn-off energy	E_{off}	-	6.0	-		
Anti-Parallel Diode Characteristics						
Diode reverse recovery time	t_{rr}	$V_R = 400\text{V}$, $I_F = 30\text{A}$, $di_F/dt = 1000\text{A}/\mu\text{s}$	-	121	-	ns
Diode reverse recovery charge	Q_{rr}		-	2300	-	μC
Diode peak reverse recovery current	I_{rm}		-	38	-	A

1 Allowed number of short circuits: < 1000; time between short circuits: > 1s.
 2 Leakage inductance L_s and Stray capacity C_s due to dynamic test circuit.

SWITCHING CHARACTERISTICS, Inductive Load at $T_j = 150^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
IGBT Characteristics						
Turn-on delay time	$t_{d(on)}$	$V_{CC}=400\text{V}$, $I_C=75\text{A}$, $V_{GE}=0/15\text{V}$, $R_G=5\Omega$, $L_{\sigma^1} = 100\text{nH}$, $C_{\sigma^1} = 39\text{pF}$ Energy losses include tail and diode reverse recovery.	-	100	-	ns
Rise time	t_r		-	70	-	
Turn-off delay time	$t_{d(off)}$		-	700	-	
Fall time	t_f		-	120	-	
Turn-on energy	E_{on}		-	6.0	-	mJ
Turn-off energy	E_{off}		-	4.6	-	
Anti-Parallel Diode Characteristics						
Diode reverse recovery time	t_{rr}	$V_R=400\text{V}$, $I_F=75\text{A}$, $di_F/dt = 1460\text{A}/\mu\text{S}$	-	182	-	ns
Diode reverse recovery charge	Q_{rr}		-	5600	-	μC
Diode peak reverse recovery current	I_{rm}		-	51.0	-	A

¹ Leakage inductance L_{σ} and Stray capacity C_{σ} due to dynamic test circuit.

Package Outline Drawing
